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## SEMICONDUCTOR IC DEVICE

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[There are no amendments to this patent.]

Claims

1. A type of semiconductor IC device characterized by the fact that a second semiconductor chip is bonded face-down on the IC forming surface of a first semiconductor chip, while a bonding pad and leads arranged on the aforementioned first semiconductor chip are connected by wires, and the aforementioned first and second semiconductor chips are sealed with a resin.

2. The semiconductor IC device described in Claim 1 characterized by the fact that the aforementioned first semiconductor chip and the aforementioned second semiconductor chip are electrically connected through bump electrodes.

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